



The vocational professional electronics manufacturing planning materials: Microelectronic Packaging Technology(Chinese Edition)

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paperback. Condition: New. Paperback. Pub Date: 2011 08 Pages: 137 Language: Chinese
Publisher: Higher Education Press Vocational electronics manufacturing class professional planning materials: microelectronic packaging technology entire body of knowledge in microelectronic packaging technology is divided into two parts. Chapter 12. The first part of the process, and the second part is a typical package. Include the introduction, wafer dicing, die attach, chip interconnect, molding, other process, dual in-line package.



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